

MC14572UB

Hex Gate

The MC14572UB hex functional gate is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. These complementary MOS logic gates find primary use where low power dissipation and/or high noise immunity is desired. The chip contains four inverters, one NOR gate and one NAND gate.

Features

- Diode Protection on All Inputs
- Single Supply Operation
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- NOR Input Pin Adjacent to V_{SS} Pin to Simplify Use As An Inverter
- NAND Input Pin Adjacent to V_{DD} Pin to Simplify Use As An Inverter
- NOR Output Pin Adjacent to Inverter Input Pin For OR Application
- NAND Output Pin Adjacent to Inverter Input Pin For AND Application
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load over the Rated Temperature Range
- Pb-Free Packages are Available*

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

| Parameter | Symbol | Value | Unit |
|---|-------------------|------------------------|------|
| DC Supply Voltage Range | V_{DD} | -0.5 to +18.0 | V |
| Input or Output Voltage Range (DC or Transient) | V_{in}, V_{out} | -0.5 to V_{DD} + 0.5 | V |
| Input or Output Current (DC or Transient) per Pin | I_{in}, I_{out} | ± 10 | mA |
| Power Dissipation, per Package (Note 1) | P_D | 500 | mW |
| Ambient Temperature Range | T_A | -55 to +125 | °C |
| Storage Temperature Range | T_{stg} | -65 to +150 | °C |
| Lead Temperature (8-Second Soldering) | T_L | 260 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating: Plastic "P and D/DW"

Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

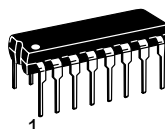
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



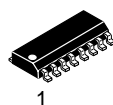
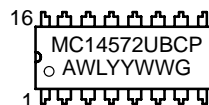
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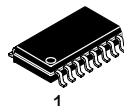
MARKING DIAGRAMS



PDIP-16
P SUFFIX
CASE 648



SOIC-16
D SUFFIX
CASE 751B



SOEIAJ-16
F SUFFIX
CASE 966



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G = Pb-Free Package

ORDERING INFORMATION

| Device | Package | Shipping† |
|---------------|-------------------|------------------|
| MC14572UBCP | PDIP-16 | 25 Units / Rail |
| MC14572UBCPG | PDIP-16 (Pb-Free) | 25 Units / Rail |
| MC14572UBD | SOIC-16 | 48 Units / Rail |
| MC14572UBDG | SOIC-16 (Pb-Free) | 48 Units / Rail |
| MC14572UBDR2 | SOIC-16 | 2500/Tape & Reel |
| MC14572UBDR2G | SOIC-16 (Pb-Free) | 2500/Tape & Reel |
| MC14572UBF | SOEIAJ-16 | 50 Units / Rail |

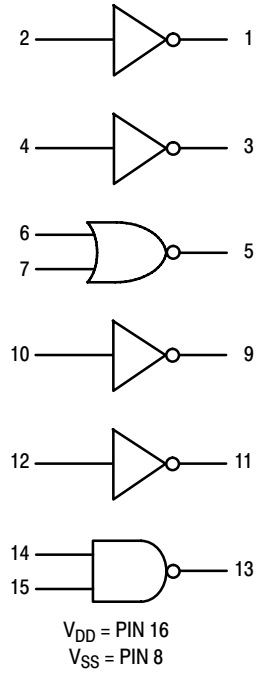
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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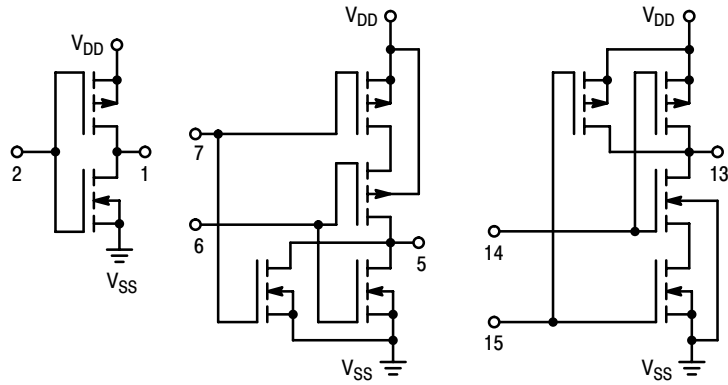
PIN ASSIGNMENT

| | | | |
|-------------------|-----|----|-------------------|
| OUT _A | 1 ● | 16 | V _{DD} |
| IN _A | 2 | 15 | IN 2 _F |
| OUT _B | 3 | 14 | IN 1 _F |
| IN _B | 4 | 13 | OUT _F |
| OUT _C | 5 | 12 | IN _E |
| IN 1 _C | 6 | 11 | OUT _E |
| IN 2 _C | 7 | 10 | IN _D |
| V _{SS} | 8 | 9 | OUT _D |

LOGIC DIAGRAM



CIRCUIT SCHEMATIC



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ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

[illegible]

2. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

3. The formulas given are for the typical characteristics only at 25°C.

4. To calculate total supply current at loads other than 50 pF: $I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$ where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and $k = 0.006$.

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SWITCHING CHARACTERISTICS (Type 5) ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$)

| Characteristic | Symbol | V_{DD} | Min | Typ (Note 6) | Max | Unit |
|--|--------------------|-----------------|-------------|-----------------|-------------------|------|
| Output Rise Time $t_{TLH} = (3.0 \text{ ns/pF}) C_L + 30 \text{ ns}$ $t_{TLH} = (1.5 \text{ ns/pF}) C_L + 15 \text{ ns}$ $t_{TLH} = (1.1 \text{ ns/pF}) C_L + 10 \text{ ns}$ | t_{TLH} | 5.0 10 15 | — — — | 180 90 65 | 360 180 130 | ns |
| Output Fall Time $t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$ | t_{THL} | 5.0 10 15 | — — — | 100 50 40 | 200 100 80 | ns |
| Propagation Delay Time $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 5 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 17 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 15 \text{ ns}$ | t_{PLH}, t_{PHL} | 5.0 10 15 | — — — | 90 50 40 | 180 100 80 | ns |

5. The formulas given are for the typical characteristics only at 25°C .

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

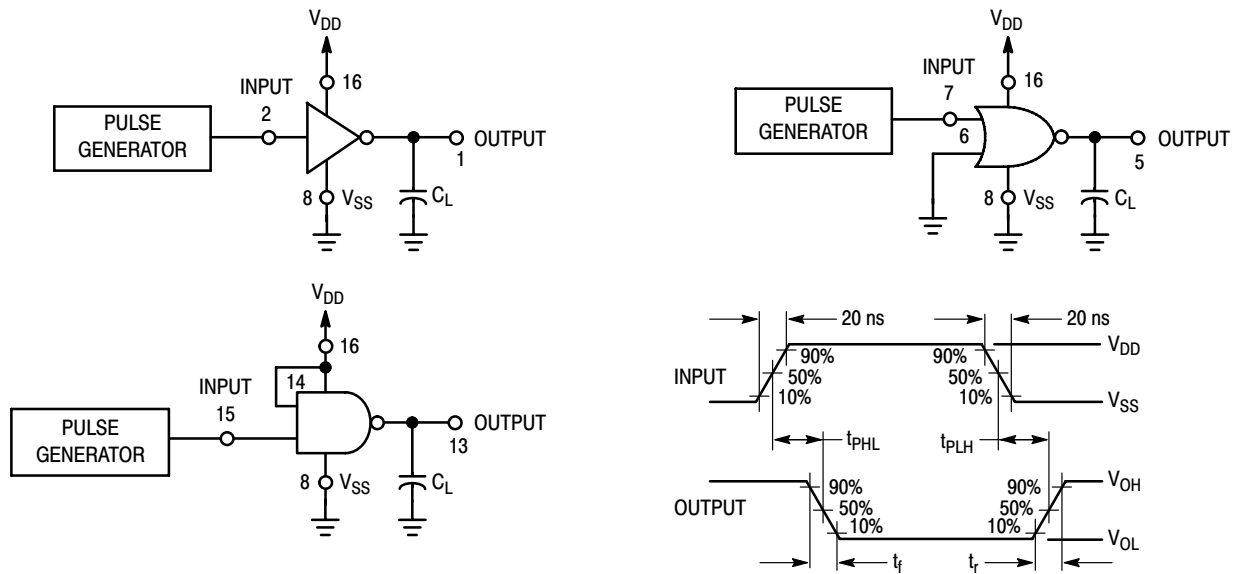
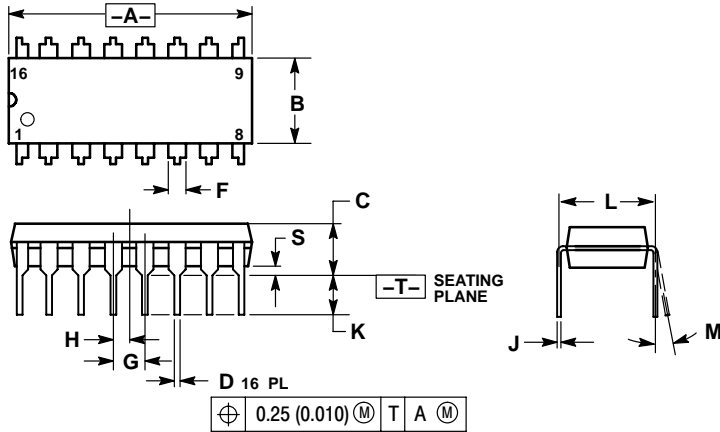


Figure 1. Switching Time Test Circuits and Waveforms

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PACKAGE DIMENSIONS

PDIP-16
CASE 648-08
ISSUE T

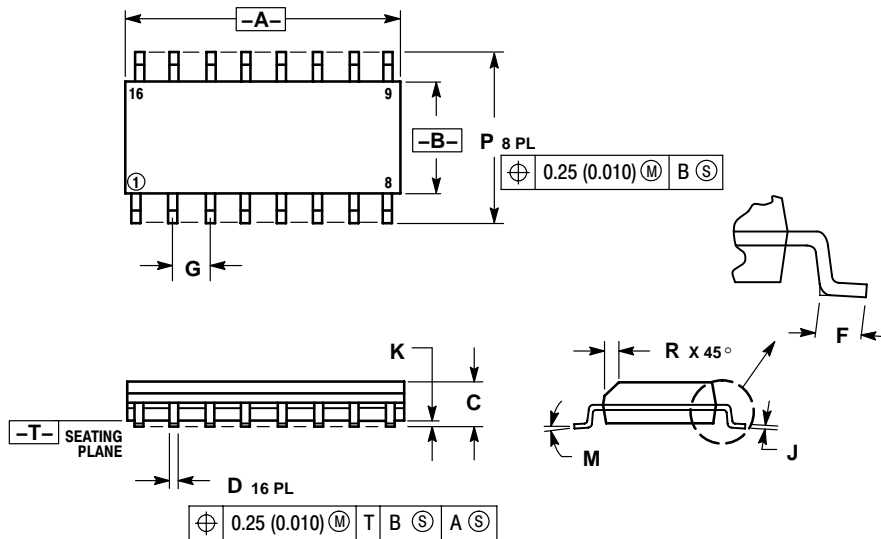


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

| DIM | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.740 | 0.770 | 18.80 | 19.55 |
| B | 0.250 | 0.270 | 6.35 | 6.85 |
| C | 0.145 | 0.175 | 3.69 | 4.44 |
| D | 0.015 | 0.021 | 0.39 | 0.53 |
| F | 0.040 | 0.70 | 1.02 | 1.77 |
| G | 0.100 BSC | | 2.54 BSC | |
| H | 0.050 BSC | | 1.27 BSC | |
| J | 0.008 | 0.015 | 0.21 | 0.38 |
| K | 0.110 | 0.130 | 2.80 | 3.30 |
| L | 0.295 | 0.305 | 7.50 | 7.74 |
| M | 0° | 10° | 0° | 10° |
| S | 0.020 | 0.040 | 0.51 | 1.01 |

SOIC-16
CASE 751B-05
ISSUE J



NOTES:

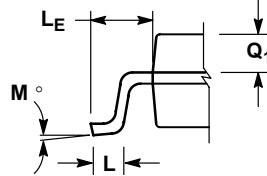
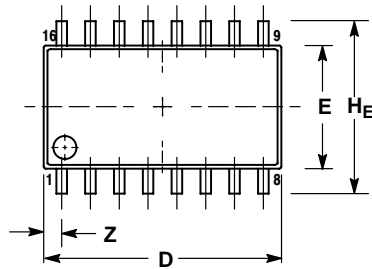
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 9.80 | 10.00 | 0.386 | 0.393 |
| B | 3.80 | 4.00 | 0.150 | 0.157 |
| C | 1.35 | 1.75 | 0.054 | 0.068 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.40 | 1.25 | 0.016 | 0.049 |
| G | 1.27 BSC | | 0.050 BSC | |
| J | 0.19 | 0.25 | 0.008 | 0.009 |
| K | 0.10 | 0.25 | 0.004 | 0.009 |
| M | 0° | 7° | 0° | 7° |
| P | 5.80 | 6.20 | 0.229 | 0.244 |
| R | 0.25 | 0.50 | 0.010 | 0.019 |

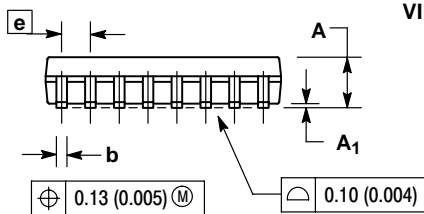
MC14572UB

PACKAGE DIMENSIONS

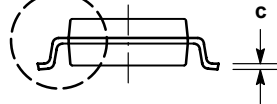
SOEIAJ-16
CASE 966-01
ISSUE A



DETAIL P




VIEW P



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

| DIM | MILLIMETERS | | INCHES | |
|----------------|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | --- | 2.05 | --- | 0.081 |
| A ₁ | 0.05 | 0.20 | 0.002 | 0.008 |
| b | 0.35 | 0.50 | 0.014 | 0.020 |
| c | 0.10 | 0.20 | 0.007 | 0.011 |
| D | 9.90 | 10.50 | 0.390 | 0.413 |
| E | 5.10 | 5.45 | 0.201 | 0.215 |
| e | 1.27 BSC | | 0.050 BSC | |
| H _E | 7.40 | 8.20 | 0.291 | 0.323 |
| L | 0.50 | 0.85 | 0.020 | 0.033 |
| L _E | 1.10 | 1.50 | 0.043 | 0.059 |
| M | 0° | 10° | 0° | 10° |
| Q ₁ | 0.70 | 0.90 | 0.028 | 0.035 |
| Z | --- | 0.78 | --- | 0.031 |

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